

U.S.S.N. 10/811,621

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Claim Amendments

Please amend claims 1, 2, 4-7, 9, 12, 13, 21-24 as follows:

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Listing of Claims

1. (currently amended) An electrochemical plating system
electrolyte bath, comprising:

 a metal electroplating electrolyte solution, said
 electrolyte solution contained in an electrolyte bath container;
 and

 a composition comprising an organic acid and a non-
 ionic polymer mixed with said organic acid, said non-ionic
 polymer selected from the group consisting of an alkoxylated
 alcohol, an alkoxylated amine, and an alkylphenol alkoxylate;

 wherein said composition is disposed as consists of a
 suspended layer within said electrolyte solution, said suspended
 layer spanning consisting of a continuous layer extending across
a dimension of said electrolyte solution in said electrolyte bath
 container, said suspended layer of sufficient dimension to form a
 wetting layer on a substrate as said substrate is passed through
 said suspended layer into said electrolyte solution, said
 electrochemical plating system electrolyte bath further
 comprising an anode in said electrolyte solution to carry out

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~~said metal electroplating in said electrolyte solution on said substrate comprising said wetting layer.~~

2. (currently amended) The ~~electrolyte bath system~~ of claim 1 wherein said organic acid is selected from the group consisting of citric acid and acetic acid.

3. (canceled)

4. (currently amended) The ~~electrolyte bath system~~ of claim 1 wherein said composition is present in said electrolyte solution in a concentration of about 5 % by weight.

5. (currently amended) The ~~electrolyte bath system~~ of claim 1 wherein said non-ionic polymer has a molecular weight of less than 1,000.

6. (currently amended) The ~~electrolyte bath system~~ of claim 5 wherein said organic acid is selected from the group consisting of citric acid and acetic acid.

7. (currently amended) The ~~electrolyte bath system~~ of claim 1 wherein said organic acid is present in said composition in a

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wt.% of about 10, and wherein said non-ionic polymer is present in said composition in a wt.% of about 5.

8. (canceled)

9. (currently amended) An ~~electrolyte bath~~ electrochemical plating system, comprising:

a copper electroplating electrolyte solution, said electrolyte solution contained in an electrolyte bath container; and

a composition comprising an organic acid and a non-ionic polymer, said non-ionic polymer having a molecular weight of less than 1,000, said non-ionic polymer mixed with said organic acid, said non-ionic polymer selected from the group consisting of an alkoxylated alcohol, alkoxylated amine, and an alkylphenol alkoxylate, said organic acid selected from the group consisting of citric acid and acetic acid;

wherein said composition ~~is disposed as~~ consists of a suspended layer within said electrolyte solution, said suspended layer spanning consisting of a continuous layer extending across

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a dimension of said electrolyte solution in said electrolyte bath container, said suspended layer of sufficient dimension to form a wetting layer on a substrate as said substrate is passed through said suspended layer into said electrolyte solution, said electrochemical plating system electrolyte bath further comprising an anode in said electrolyte solution to carry out said copper electroplating in said electrolyte solution on said substrate comprising said wetting layer.

10. (canceled)

11. (canceled)

12. (currently amended) The ~~electrolyte bath system~~ of claim 9 wherein said composition is present in said electrolyte solution in a concentration of about 5% by weight.

13. (currently amended) The ~~electrolyte bath system~~ of claim 9 wherein said organic acid is present in said composition in a wt.% of about 10, and wherein said non-ionic polymer is present in said composition in a wt.% of about 5.

Claims 14-20 (canceled)

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21. (currently amended) The ~~electrolyte bath~~ system of claim 1, wherein said non-ionic polymer is present in said composition in a quantity of from about 0.5 to about 10 wt. %.

22. (currently amended) The ~~electrolyte bath~~ system of claim 1, wherein said organic acid is present in said composition in a quantity of from about 2 to about 20 wt. %.

23. (currently amended) The ~~electrolyte bath~~ system of claim 9, wherein said non-ionic polymer is present in said composition in a quantity of from about 0.5 to about 10 wt. %.

24. (currently amended) The ~~electrolyte bath~~ system of claim 9, wherein said organic acid is present in said composition in a quantity of from about 2 to about 20 wt. %.

25. (canceled)

26. (canceled)